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TITLE : ELECTRICALLY CONDUCTIVE ADHESIVE

ABSTRACT : PURPOSE: A solderable, electrically conductive adhesive, excellent in electrical conductivity and suitable for a printed wiring, composed of a copper powder, a soldering powder, a thermosetting resin and an activator.

CONSTITUTION: A copper powder is blended with a soldering powder of particle size  $\leq 10\mu$  which is composed of an alloy of Sn, Bi, Cd, In, etc., and partially melts at the curing temperature of a thermosetting resin, in a weight ratio of 10:5~1. The mixture is mixed with a thermosetting resin such as an epoxy or phenol resin, an activator such as abietic acid or an amine resin, and a solvent such as cyclohexanol. The adhesive is excellent in electrical conductivity and adhesion, and free from aging of electrical conductivity.

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